IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg In	formatio	on	
upplier Infor	mation													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi											2025-05-18			
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stev	wards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
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Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Reques	ster Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Anufacturing Site	Weig	ht*	UOM	Unit Type
		ES2B UFR SM		UFR SMB PN 2A 1	JFR SMB PN 2A 100V		2025-05-18		Т	TSCBE			mg	Each
	g Process Informati		lamain al De	Alley	CTD 020 Met	Dating	Dools Pro-	age Dody T		Mov Time at Perla	Townsoroto	Normala -	or of Deflow Co-	las
2		<u> </u>		STD-020 MSL	Kating	Peak Process Body Tempe		emperatur				er of Reflow Cyc	ies	
•	1111 (Sn) - annealed		CU Alloy	1			260		IC.	30	seconds	3		
omments			1 10.1	0										
	n time at peak temperatur													
c more informa	ition regarding material c	omposition j	piease refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, so of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of heat agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.764	mg	Supplier	Silicon (Si)	7440-21-3		0.6876	mg
			В	Nickel (Ni)	7440-02-0		0.005	mg
			Supplier	Gold (Au)	7440-57-5		0.0011	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0703	mg
Die Attach Solder	2.25	mg	Supplier	Silver (Ag)	7440-22-4		0.0563	mg
			A	Lead (Pb)	7439-92-1	7a	2.0812	mg
			Supplier	Tin (Sn)	7440-31-5		0.1125	mg
Lead Frame	34.0437	mg	Supplier	Iron (Fe)	7439-89-6		0.0409	mg
			Supplier	Copper (Cu)	7440-50-8		33.9926	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0102	mg
Mold Compound-Black	54.234	mg		Metal Hydroxide	proprietary data		1.8982	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.3387	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2712	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		43.3872	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.3387	mg
Plating	0.7083	mg	Supplier	Tin (Sn)	7440-31-5		0.7083	mg